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April 2016

FAN7171_F085 High-Current High-Side Gate Drive IC

Features

- Automotive qualified to AEC Q100
- Floating Channel for Bootstrap Operation to +600 V
- 4 A Sourcing and 4 A Sinking Current Driving Capability
- Common-Mode dv/dt Noise-Cancelling Circuit
- 3.3 V and 5 V Input Logic Compatible
- Output In-phase with Input Signal
- Under- Voltage Lockout for VBS
- 25 V Shunt Regulator on VDD and VBS
- 8-Lead, Small Outline Package

Applications

- Common Rail Injection Systems
- DC-DC Converter
- Motor Drive (Electric Power Steering, Fans)

Related Product Resources

- FAN7171_F085 Product Folder
- AN-6076 Design and Application Guide of Bootstrap Circuit for High-Voltage Gate-Drive IC
- AN-8102 200 Recommendations to Avoid Short Pulse Width Issues in HVIC Gate Driver Applications
- AN-9052 Design Guide for Selection of Bootstrap Components
- AN-4171 FAN7085 High-Side Gate Driver- Internal Recharge Path Design Considerations

Description

The FAN7171_F085 is a monolithic high-side gate drive IC that can drive high-speed MOSFETs and IGBTs that operate up to +600 V. It has a buffered output stage with all NMOS transistors designed for high pulse current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise-canceling techniques provide stable operation of the high-side driver under high-dv/dt noise circumstances. An advanced level-shift circuit offers high-side gate driver operation up to V_S =-9.8 V (typical) for V_{BS} =15 V.

The UVLO circuit prevents malfunction when V_{BS} is lower than the specified threshold voltage.

The high-current and low-output voltage-drop feature make this device suitable for sustaining switch drivers and energy-recovery switch drivers in automotive motor drive inverters, switching power supplies, and high-power DC-DC converter applications.



Figure 1. 8-Lead, SOIC, Narrow Body

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method			
FAN7171M_F085		8-Lead, Small Outline Integrated Circuit	Tube			
FAN7171MX_F085	-40°C ~ 125°C	(SOIC), JEDEC MS-012, .150 inch Narrow Body	Tape & Reel			

Note:

- 1. These devices passed wave soldering test by JESD22A-111.
- 2. A suffix as "...F085P" has been temporarily introduced in order to manage a double source strategy as Fairchild has officially announced in Aug 2014.

Typical Application

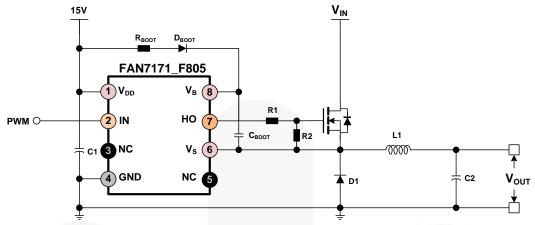


Figure 2. Typical Application

Block Diagram

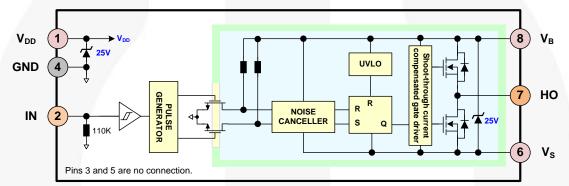


Figure 3. Block Diagram

Pin Configuration

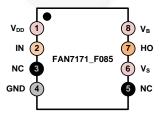


Figure 4. Pin Assignment (Top Through View)

Pin Descriptions

Pin #	Name	Description
1	V_{DD}	Supply Voltage
2	IN	Logic Input for High-Side Gate Driver Output
3	NC	No Connection
4	GND	Ground
5	NC	No Connection
6	Vs	High-Voltage Floating Supply Return
7	НО	High-Side Driver Output
8	V _B	High-Side Floating Supply

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Characteristics	Min.	Max.	Unit
Vs	High-Side Floating Offset Voltage	V _B -V _{SHUNT}	V _B +0.3	V
V _B	High-Side Floating Supply Voltage ⁽³⁾	-0.3	625.0	V
V _{HO}	High-Side Floating Output Voltage	V _S -0.3	V _B +0.3	V
V_{DD}	Low-Side and Logic Supply Voltage ⁽³⁾	-0.3	V _{SHUNT}	V
V _{IN}	Logic Input Voltage	-0.3	V _{DD} +0.3	V
dV _S /dt	Allowable Offset Voltage Slew Rate		±50	V/ns
P _D	Power Dissipation ^(4,5,6)		0.625	W
$\theta_{\sf JA}$	Thermal Resistance		200	°C/W
TJ	Junction Temperature	-55	150	°C
T _{STG}	Storage Temperature	-55	150	°C
T _A	Operating Ambient Temperature	-40	125	°C
ECD.	Human Body Model (HBM)		1500	V
ESD	Charge Device Model (CDM)		500	V

Notes:

- This IC contains a shunt regulator on V_{DD} and V_{BS} with a normal breakdown voltage of 25 V. Please note that this supply pin should not be driven by a low-impedance voltage source greater than the V_{SHUNT} specified in the Electrical Characteristics section.
- 4. Mounted on 76.2 x 114.3 x 1.6 mm PCB (FR-4 glass epoxy material).
- Refer to the following standards: JESD51-2: Integral circuits thermal test method environmental conditions, natural convection, and JESD51-3: Low effective thermal conductivity test board for leaded surface-mount packages.
- 6. Do not exceed power dissipation (P_D) under any circumstances.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V _{BS}	High-Side Floating Supply Voltage	V _S +10	V _S +20	V
	High-Side Floating Supply Offset Voltage (DC)	6-V _{DD}		
Vs	High-Side Floating Supply Offset Voltage (Transient)	-15 (~170)	600	V
		-7 (~400)		
V _{HO}	High-Side Output Voltage	Vs	V _B	V
V _{IN}	Logic Input Voltage	GND	V_{DD}	V
V_{DD}	Supply Voltage	10	20	V

Electrical Characteristics

 V_{BIAS} (V_{DD} , V_{BS})=15 V, -40°C \leq $T_A \leq$ 125°C, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to GND. The V_O and I_O parameters are relative to V_S and are applicable to the respective output HO.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Power Su	upply Section			I		
I_{QDD}	Quiescent V _{DD} Supply Current	V _{IN} =0 V or 5 V		25	70	μА
I_{PDD}	Operating V _{DD} Supply Current	f _{IN} =20 kHz, No Load		35	100	μΑ
Bootstra	oped Supply Section			l	ı	
V _{BSUV+}	V _{BS} Supply Under-Voltage Positive-Going Threshold Voltage	V _{BS} =Sweep	8.2	9.2	10.2	V
V _{BSUV} -	V _{BS} Supply Under-Voltage Negative-Going Threshold Voltage	V _{BS} =Sweep	7.5	8.5	9.5	V
V _{BSHYS}	V _{BS} Supply UVLO Hysteresis Voltage	V _{BS} =Sweep		0.6		V
I_{LK}	Offset Supply Leakage Current	V _B =V _S =600 V			50	μА
I _{QBS}	Quiescent V _{BS} Supply Current	V _{IN} =0 V or 5 V		60	120	μΑ
I _{PBS}	Operating V _{BS} Supply Current	C _{LOAD} =1 nF, f _{IN} =20 kHz, RMS Value		0.73	2.80	mA
Shunt Re	gulator Section			•	À	
V_{SHUNT}	V _{DD} and V _{BS} Shunt Regulator Clamping Voltage	I _{SHUNT} =5 mA	23	25		V
Input Log	gic Section (IN)					
V _{IH}	Logic "1" Input Voltage		2.5	1		V
V_{IL}	Logic "0" Input Voltage				8.0	V
I _{IN+}	Logic Input High Bias Current	V _{IN} =5 V		45	125	μΑ
I _{IN-}	Logic Input Low Bias Current	V _{IN} =0 V			2	μΑ
R _{IN}	Input Pull-down Resistance		40	110		kΩ
Gate Driv	er Output Section (HO)					
V _{OH}	High Level Output Voltage (V _{BIAS} - V _O)	No Load	- 1		1.5	V
V_{OL}	Low Level Output Voltage	No Load			35	mV
I _{O+}	Output High, Short-Circuit Pulsed Current ⁽⁷⁾	V _{HO} =0 V, V _{IN} =5 V, PW ≤10 μs	3.0	4.0		Α
I _O -	Output Low, Short-Circuit Pulsed Current ⁽⁷⁾	V _{HO} =15 V,V _{IN} =0 V, PW ≤10 μs	3.0	4.0		Α
Vs	Allowable Negative V _S Pin Voltage for IN Signal Propagation to HO			-9.8	-7.0	V

Note:

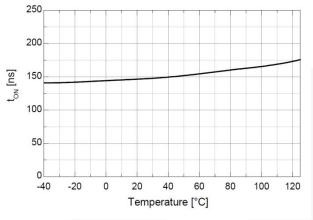
7. These parameters guaranteed by design.

Dynamic Electrical Characteristics

V_{BIAS} (V_{DD}, V_{BS}) =15 V, V_S=GND=0 V, C_L=1000 pF, and-40°C ≤ T_A ≤ 125°C, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ton	Turn-On Propagation Delay	V _S =0 V		150	210	ns
t _{OFF}	Turn-Off Propagation Delay	V _S =0 V		150	210	ns
t _R	Turn-On Rise Time			25	50	ns
t _F	Turn-Off Fall Time			15	45	ns

Typical Performance Characteristics



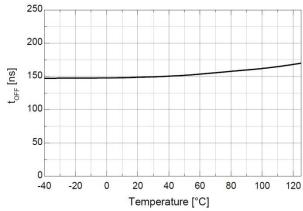


Figure 5. Turn-On Propagation Delay vs. Temperature

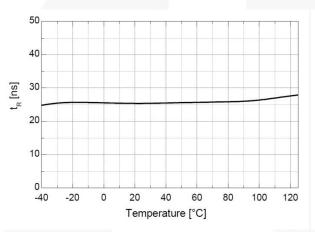


Figure 6. Turn-Off Propagation Delay vs. Temperature

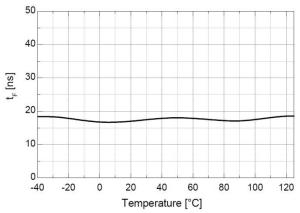


Figure 7. Turn-On Rise Time vs. Temperature

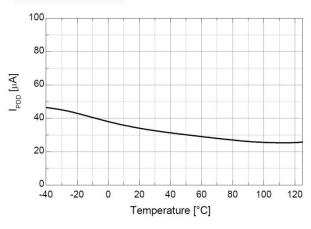


Figure 8. Turn-Off Fall Time vs. Temperature

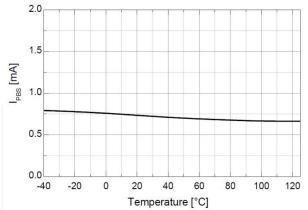
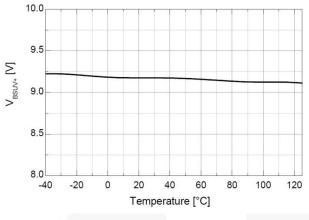


Figure 9. Operating V_{DD} Supply Current vs. Temperature

Figure 10. Operating V_{BS} Supply Current vs. Temperature

Typical Performance Characteristics



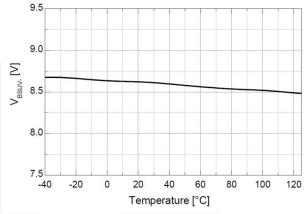
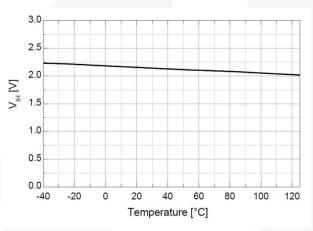


Figure 11. V_{BS} UVLO+ vs. Temperature

Figure 12. V_{BS} UVLO- vs. Temperature



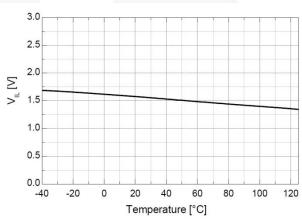
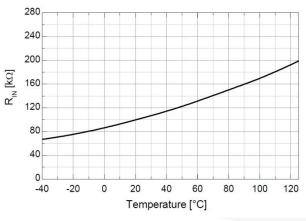


Figure 13. Logic High Input Voltage vs. Temperature Figure 14. Logic Low Input Voltage vs. Temperature



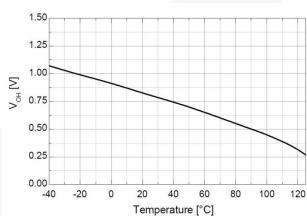


Figure 15. Input Pull-Down Resistance vs. Temperature

Figure 16. High-Level Output Voltage vs. Temperature

Typical Performance Characteristics

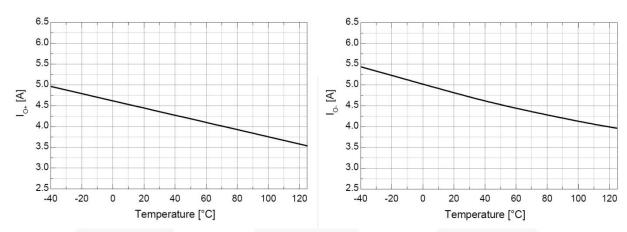


Figure 17. Output High, Short-Circuit Pulsed Current Figure 18. Output Low, Short-Circuit Pulsed Current vs. Temperature

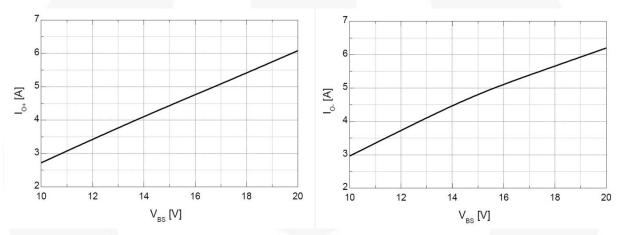


Figure 19. Output High, Short-Circuit Pulsed Current Figure 20. Output Low, Short-Circuit Pulsed Current vs. Supply Voltage vs. Supply Voltage

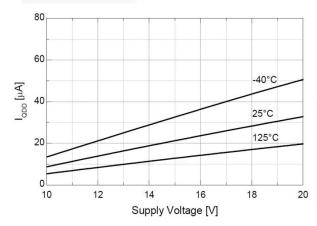


Figure 21. Quiescent V_{DD} Supply Current vs. Supply Voltage

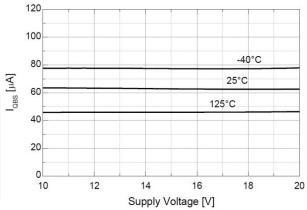


Figure 22. Quiescent V_{BS} Supply Current vs. Supply Voltage

Switching Time Definitions

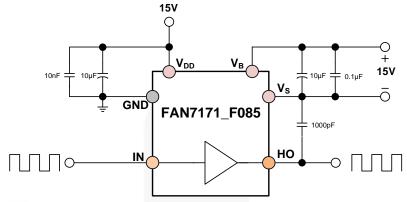


Figure 23. Switching Time Test Circuit (Referenced 8-SOIC)

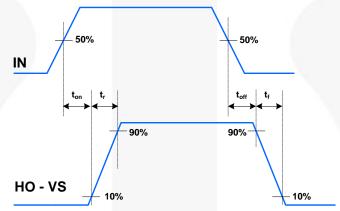


Figure 24. Switching Time Waveform Definitions

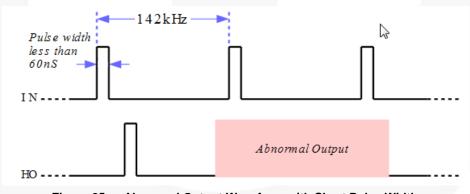
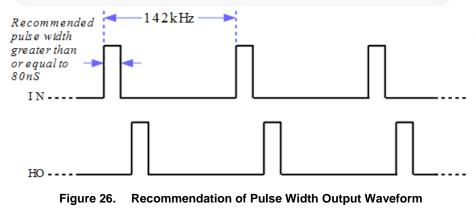
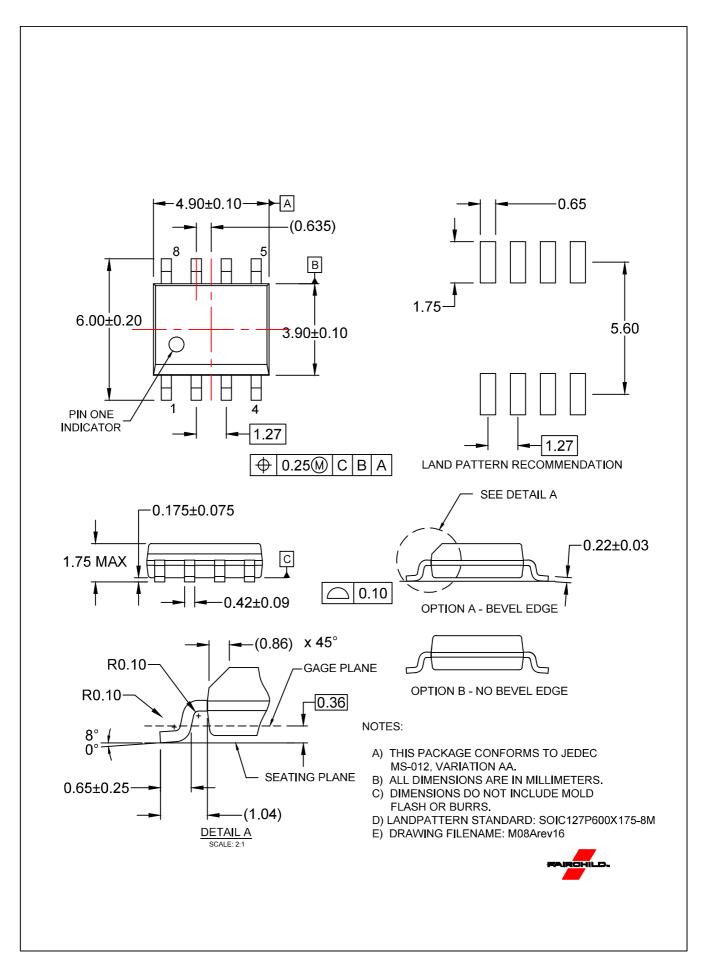


Figure 25. Abnormal Output Waveform with Short Pulse Width





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